

**WHAT IS CLAIMED IS:**

1. A carrier mechanism for an image sensor package, the carrier is for fixing the transparent layer of the image sensor, the carrier mechanism comprising:

5 a substrate formed with an upper surface, a lower surface, and plural penetrated slots through the upper surface to the lower surface of the substrate, at the periphery of the each penetrated slot of the substrate being formed with plural fixing regions, then the transparent layer is not contact with the upper surface of the substrate ; and

10 a plurality of positioned post being fixed at the fixing region of the substrate to fix the periphery of the transparent layer.

2. The carrier mechanism according to claim 1, wherein plural penetrated slots are a shaped of an octagon, then the fixing regions is located at the corresponding to angle of the octagon.

15 3. The carrier mechanism according to claim 1, wherein the plural positioned posts are integrated formed with the substrate.

4. The carrier mechanism according to claim 1, wherein the each fixing region has tow fixed post.